

## Mega Etch 7300 Specifications

Etcher Unit	Height: 431 mm (17 in)
	Width: 330 mm (13 in)
	Depth: 483 mm (19 in)
Bottle Assembly	Height: 254 mm (10 in)
	Width: 280 mm (11 in)
	Depth: 127 mm (5 in)
Weight	Approx. 18 kg (40 lb)
Power Source	90 to 250 VAC, 50 to 60 Hz (4 amp)
Acid temp. range	10° to 250° C
Acid temp. set point	1° C ± 1% of setting
Etch cavity (up to)	22 mm x 22 mm (30 mm diagonal) for any packages mounted on or off a PCB.
	Maximum board size is 152.5 x 152.5 mm (6 x 6 in)
Choice of Acids	fuming nitric acids, mixed fuming nitric and sulfuric acids, or fuming/concentrated sulfuric acid
Acid Mix Ratios	(nitric to sulfuric ratios) 9:1, 6:1, 5:1, 4:1, 7:2, 3:1, 5:2, 2:1, 3:2, 1:1, 1:2, 1:3, 1:4, 1:5
Post Etch Rinse Options	sulfuric acids, fuming nitric acids, mixed acids, or no rinse
Etch Times	1 to 2,400 seconds in 1 second increments (1 seconds to 40 minutes) dynamic (real time) adjustments of etch time
Etch Modalities	Pulse Etch, Reciprocal Etch Acid Pulse (REAP)
Temperature Ranges	20° to 90° C (nitric acid), 20° to 250° C (sulfuric acid), 10° to 100° C (mixed acids)
Etchant Volume Selection	1 to 8 ml per minute - for all acids & acid mixes at a temperature above 100° C $$
Operator Program Storage	100 programs stored to nonvolatile memory
Ambient Temperature Range	15° to 26° C
Warranty	most comprehensive and inclusive warranty in industry (ask for full details)